

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

**Please CANCEL claim 17, AMEND claims 13, 14, 16 and 19, and ADD new claims 20-27 in accordance with the following:**

1-9. (Cancelled)

10. (Previously Presented) A mold releasing film for printed circuit board production, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, wherein the elastomer (F) is (G) a partially hydrogenated polymer of a block copolymer of an aromatic vinyl compound and a conjugated diene compound.

11. (Original) The mold releasing film for printed circuit board production according to claim 10, wherein the content of a bonded aromatic vinyl compound in component (G) is from 5 wt% to 65 wt%.

12. (Previously Presented) A mold releasing film for printed circuit board production, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, wherein the elastomer (F) is (H) a copolymer of ethylene and a vinyl ester compound.

13. (Currently Amended) The mold releasing film for printed circuit board production according to claim ~~10~~7, obtained by molding through an extrusion tubular method.

14. (Currently Amended) The mold releasing film for printed circuit board production according to claim ~~10~~7, obtained by molding through a T-die extrusion method.

15. (Previously Presented) A mold releasing film for printed circuit board production,

which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, the mold releasing film having a contact angle between the film surface of its outermost surface layer and a water drop of 80° or more.

16. (Currently Amended) The mold releasing film for printed circuit board production according to claim 10~~7~~, wherein the printed circuit board is a flexible printed circuit board.

17. (Cancelled)

18. (Previously Presented) A method for producing a printed circuit board comprising hot-pressing a copper-clad laminate or a copper foil and a prepreg or a heat-resistant film along with a mold-releasing film,

wherein the mold releasing film is a film comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more.

19. (Currently Amended) The mold releasing film for printed circuit board production according to claim 10~~7~~, wherein the mold releasing film has a thickness of from 50 to 300  $\mu\text{m}$ .

20. (New) The mold releasing film for printed circuit board production according to claim 12, obtained by molding through an extrusion tubular method.

21. (New) The mold releasing film for printed circuit board production according to claim 15, obtained by molding through an extrusion tubular method.

22. (New) The mold releasing film for printed circuit board production according to claim 12, obtained by molding through a T-die extrusion method.

23. (New) The mold releasing film for printed circuit board production according to claim 15, obtained by molding through a T-die extrusion method.

24. (New) The mold releasing film for printed circuit board production according to claim 12, wherein the printed circuit board is a flexible printed circuit board.

25. (New) The mold releasing film for printed circuit board production according to claim 15, wherein the printed circuit board is a flexible printed circuit board.

26. (New) The mold releasing film for printed circuit board production according to claim 12, wherein the mold releasing film has a thickness of from 50 to 300  $\mu\text{m}$ .

27. (New) The mold releasing film for printed circuit board production according to claim 15, wherein the mold releasing film has a thickness of from 50 to 300  $\mu\text{m}$ .

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